



Modelling of thermal load and electric fields in microfocus X-ray tubes

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X-RAY WorX GmbH

Innovative Microfocus X-ray Tubes - Made in Germany

Outlook



- X-RAY WorX
- Fields of business
- Microfocus X-Ray technology
- Comsol application by X-Ray WorX:
 - Optimization of thermal load on HV-Insulators (ht & sm)
 - Optimization of thermal load on the target (ht & sm)
 - Optimization of aperture diameter and filament position incl. particle tracing (es & pt)
 - Optimization of the geometry of the cathode chamber and cathode assembly (es)
- Summary

X-RAY WorX



We are one of the leading global suppliers of high resolution microfocus tubes for non-destructive testing, computed tomography, and metrology in industry and science.

- ▶ In cooperation with our partners, we offer worldwide sales and services for microfocus X-ray solutions.
- ▶ It is our goal to continuously improve and enhance microfocus technology in terms of resolution, focal spot stability, power, and ease of use.



Since January 2021 X-RAY WorX is part of the Swedish Indutrade group

www.x-ray-worx.com

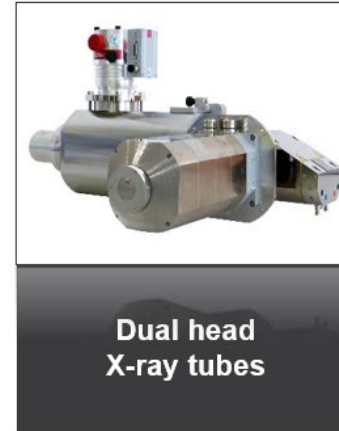


DEUTSCHE
GESELLSCHAFT FÜR
ZERSTÖRUNGSFREIE
PRÜFUNG E.V.

Fields of business



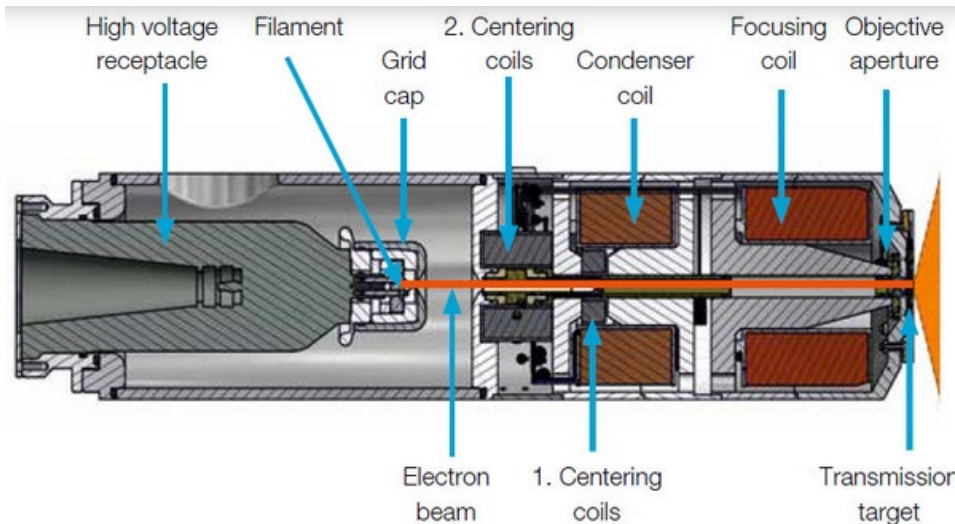
Development and production of microfocus X-ray tubes



We are continuously working on improvement of availability, reduction of focal spot movement, efficient cooling systems, higher filament lifetime, improvement of resolution and stability, automation, and maintainability.

Microfocus X-Ray technology

Microfocus transmission tubes – double stage



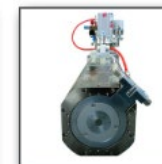
Product image



Microfocus X-ray tube XWT-160-TCNF Plus



Target with scale



XWT-190-TCNF Plus
with 50 W target power

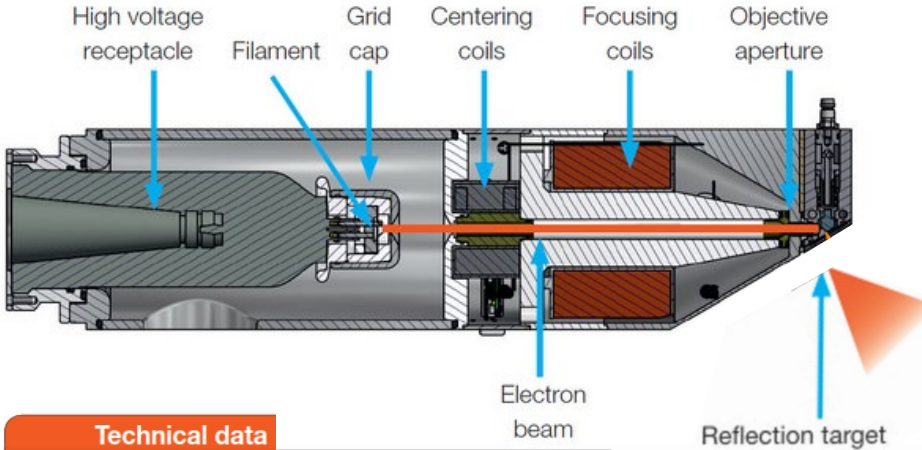


JIMA resolution 0.5 μm

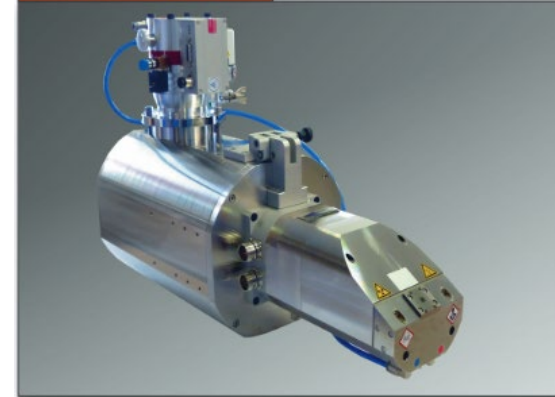
THE Plus	TCHE Plus	TCNF Plus
Up to 300kV	Up to 240kV	Up to 240kV
2μm – 15μm JIMA	0.9μm – 15μm JIMA	0.5μm – 15μm JIMA
External cooling	External cooling	Internal cooling
Diamond target	Diamond target	Diamond target
Target cooling	Target cooling	Target cooling
50W target power	50W target power	50W target power

Microfocus X-Ray technology

Microfocus reflection tubes

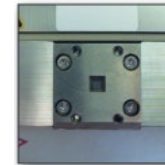


Product image



Microfocus X-ray tube XWT-300-CT Plus

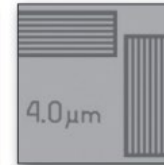
Technical data			
Data	Product line CT Plus		
Max. voltage (kV)	225	240	300
Min. voltage (kV)	20	20	50
Max. current (mA)	3.0	3.0	3.0
Min. current (mA)	0.05	0.05	0.05
Max. power, emission (Watt)	500	500	500
Max. power, target (Watt)	450	450	450
JIMA resolution (μm)	4.0	4.0	4.0
Tube type	Reflection		
Target type	High Power		
Target material	Tungsten		



XWT-300-CT Plus with new collimator



XWT-300-CT Plus with new cooling circuit



JIMA resolution 4.0 μm : 225kV - 300kV tubes

Comsol application bei X-Ray WorX

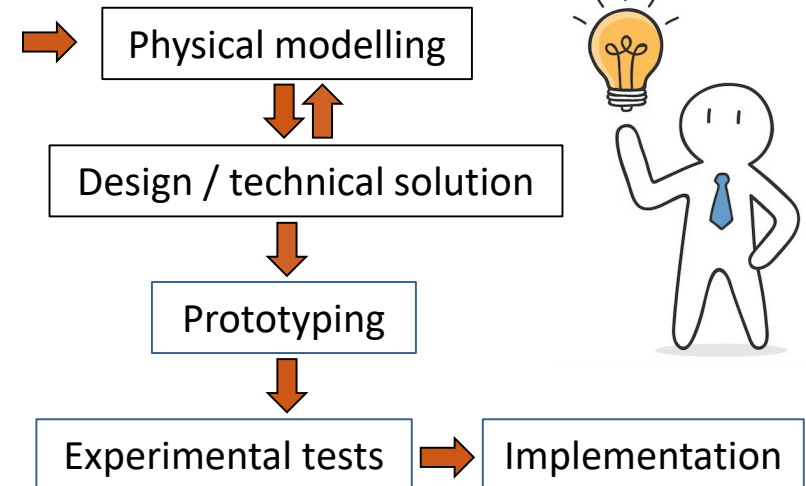


Our technical challenges

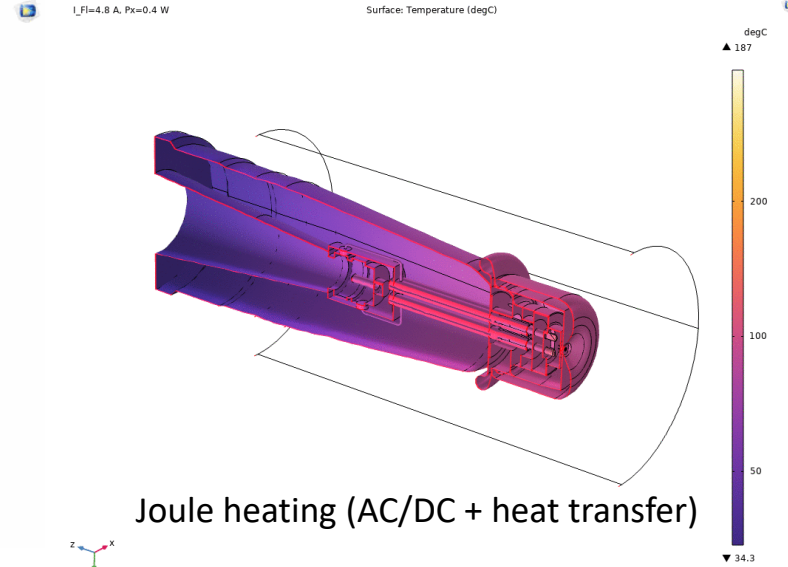
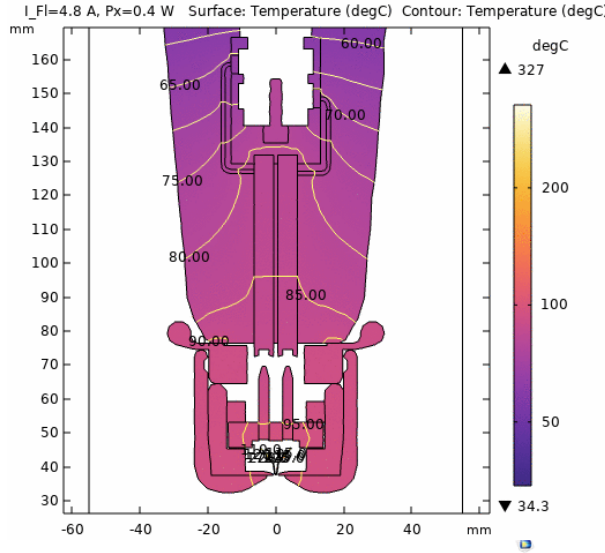
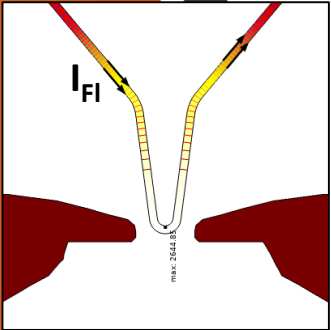
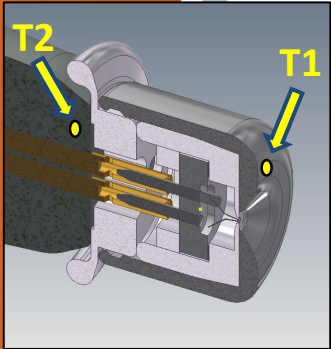
- More X-ray power: thermal load on the target (anode)
- Dielectric strength (proper materials, geometry, polishing, vacuum conditions)
- Filament lifetime: geometry, temperature, filament current, vacuum conditions
- Smaller focal spot: electron optics and thermal load on the target surface
- Smaller & lighter modules
- Long-term thermal stability (cooling and e-optics performance)

Comsol Multiphysics

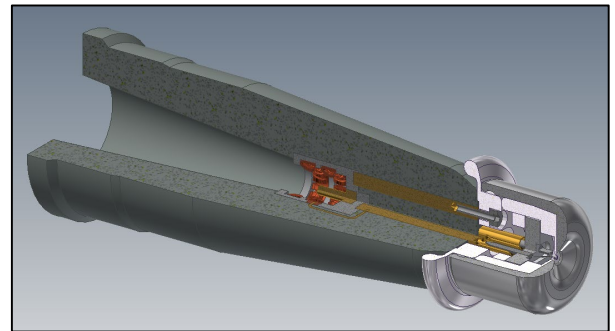
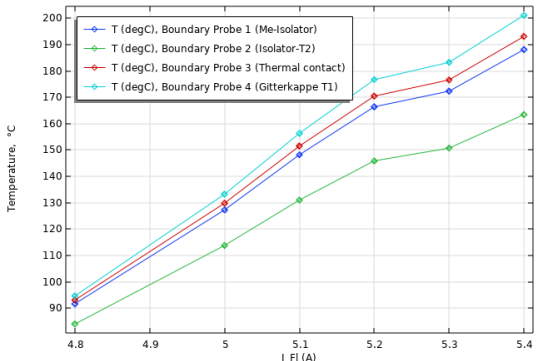
- Heat transfer
- AC/DC
- Particle tracing module
- Material library
- LiveLink™ for Inventor®
- Design module
- Structural Mechanics (optionally)



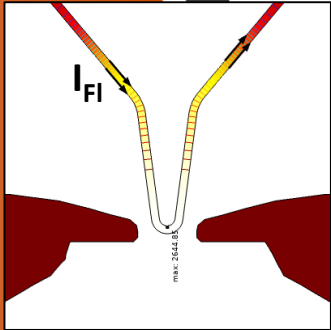
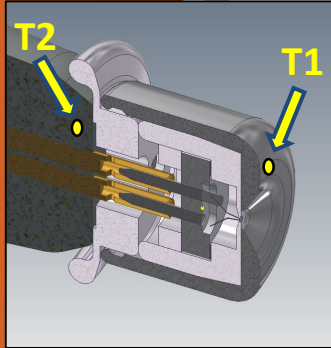
Optimization of the thermal load on HV-Insulators



Joule heating (AC/DC + heat transfer)

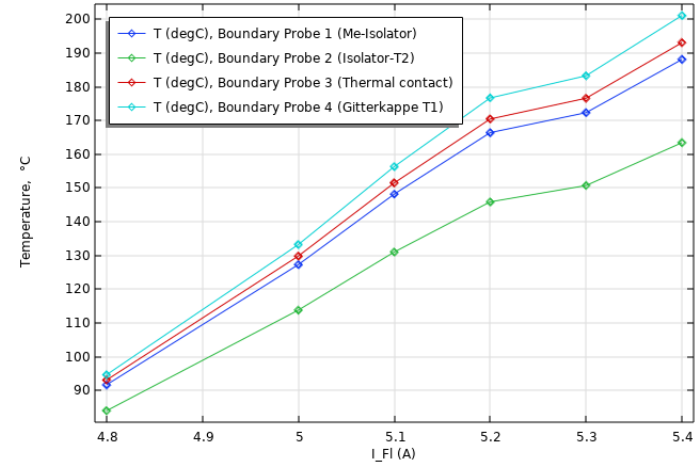


Heat transfer: experiment and modelling



Experimental data

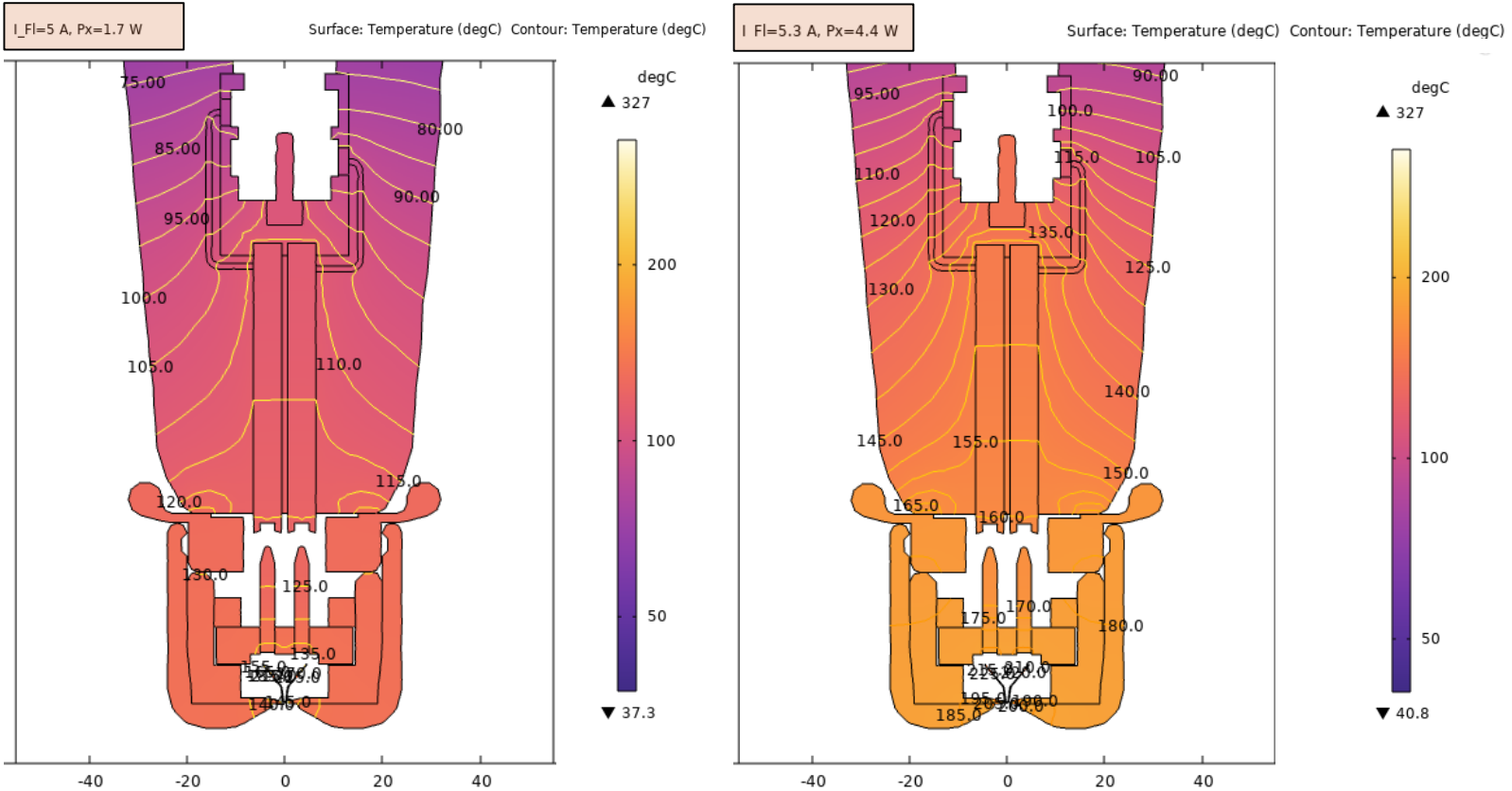
I_Fl (A)	T1 (Gitterkappe)	T2 (Isolator)
0	28,7	28,8
4,8	94,4	78,6
5,0	132,3	108
5,1	156	127,8
5,2	176,3	143
5,3	183,6	152,8
5,4	201,4	166,1



Simulation data (Boundary Probes)

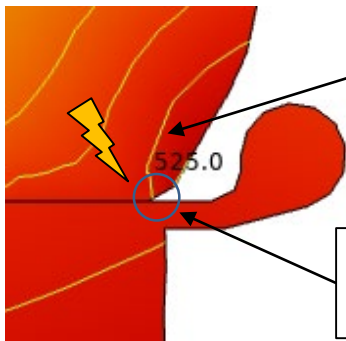
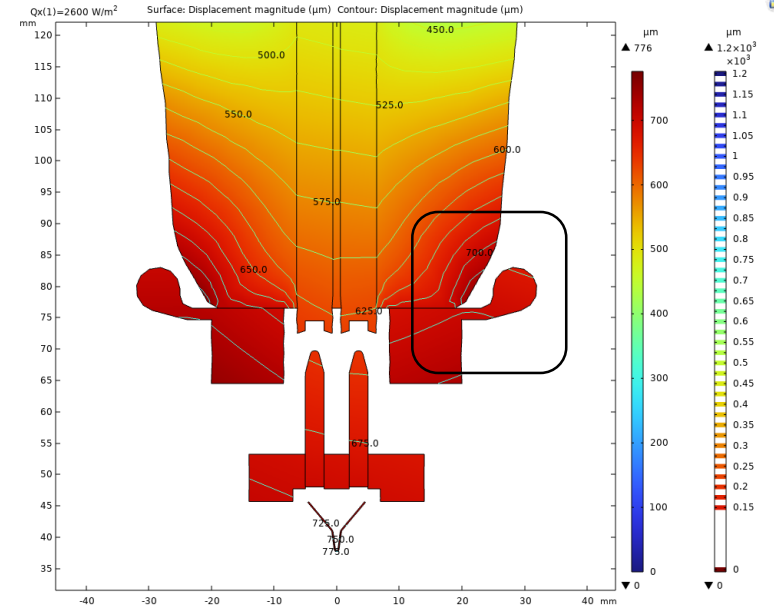
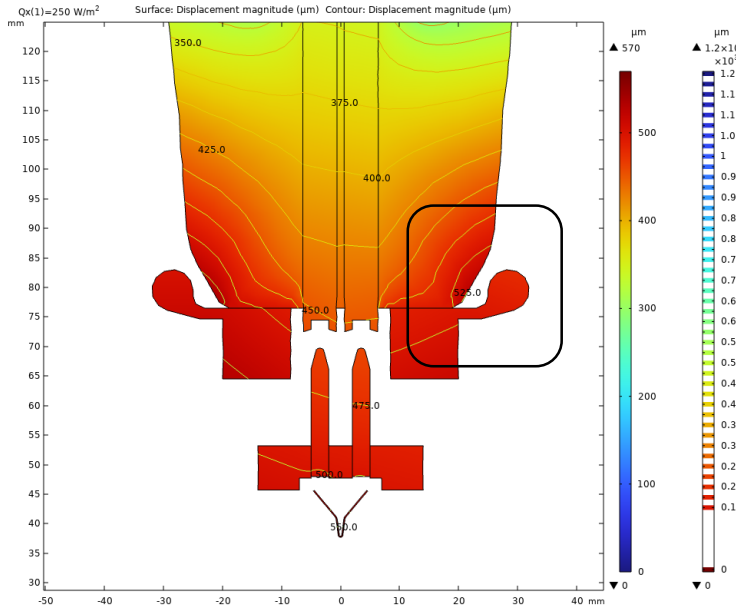
I_Fl (A)	Px (W)	T (degC) T1 (Gitterkappe)	T (degC) (Thermal contact)	T (degC) (Me-Isol)	T (degC) T2 (Isolator)
4.8	0.4	94.613	93.046	91.631	83.934
5.0	1.7	133.24	129.84	127.29	113.79
5.1	2.9	156.36	151.53	148.22	131.02
5.2	4.1	176.73	170.48	166.44	145.91
5.3	4.4	183.31	176.65	172.36	150.75
5.4	5.6	201.19	193.14	188.15	163.47

Modelling results (heat transfer)



FEM: Temperature field / thermal expansion → design optimization

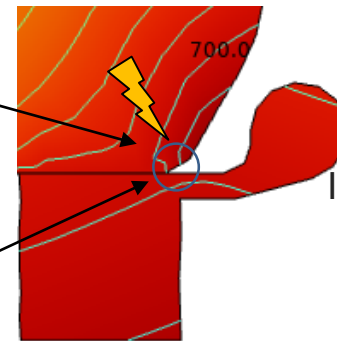
Modelling results (thermal expansion)



Thermal stress and strong deformation!?

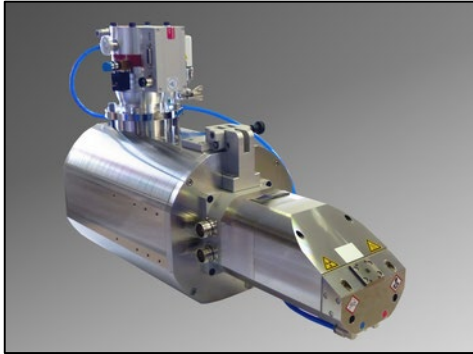
$I_{FI} = 5.0A$, ($T_2 = 108\text{ °C}$)

„Triple point“: HV breakdown / surface flashover

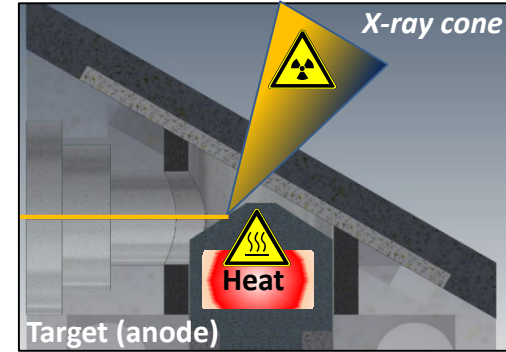


$I_{FI} = 5.3A$, ($T_2 = 153\text{ °C}$)

Optimization of thermal load on the target

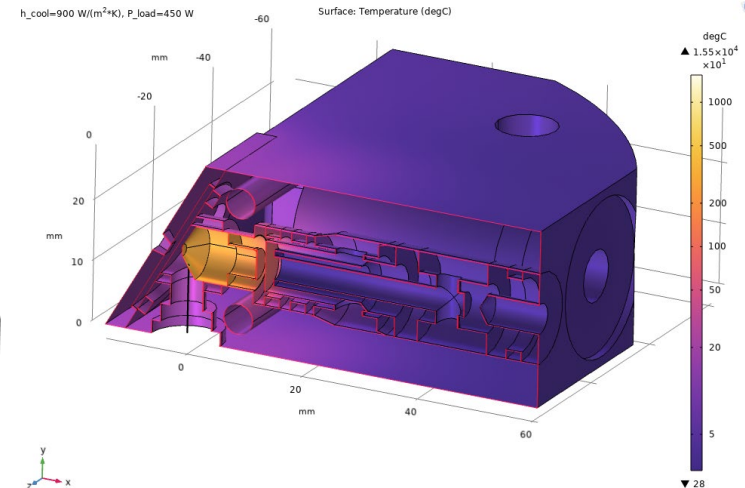
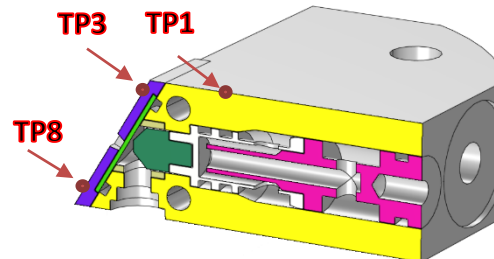


	Voltage [kV]							
	60	100	150	190	225	240	300	
50	60	60	60	60	55	40	40	40
100	110	105	100	85	80	75	75	
150	140	175	145	125	125	125	125	
200		250	190	170	170	170	170	
250		340	235	235	225	225	225	
300			300	300	285	285	285	
350			370	370	340	340	340	
400			450	450	400	400	400	
450				500	450	450	400	



Topics:

- Heat distribution within the Target (anode)
- Thermal expansion within the target-assembly
- Heat distribution within the tube housing
- Extreme temperatures at the target surface
- Active cooling

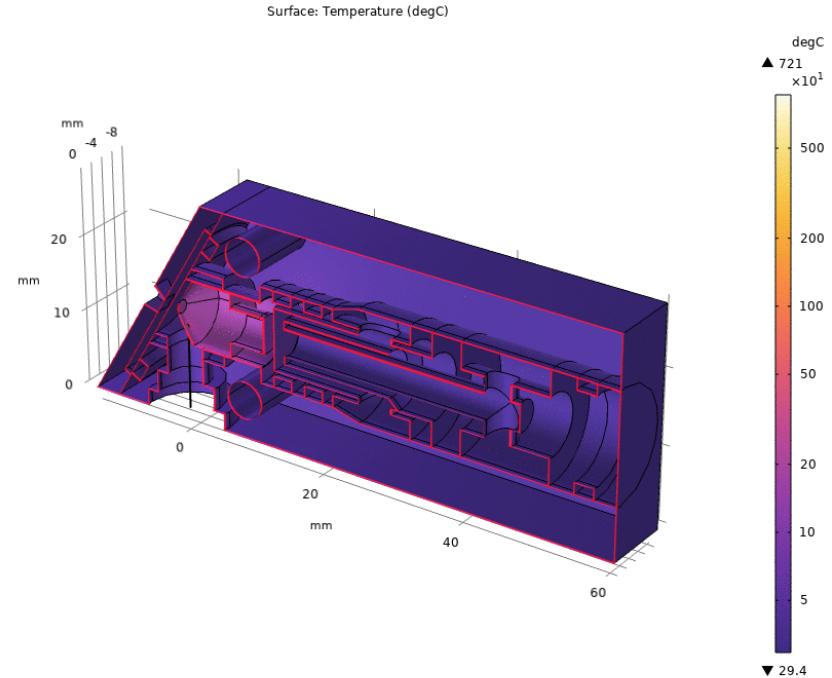
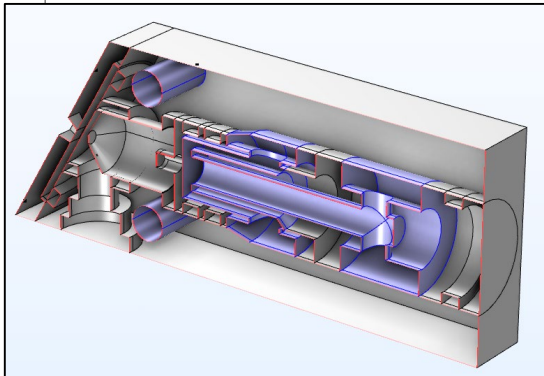
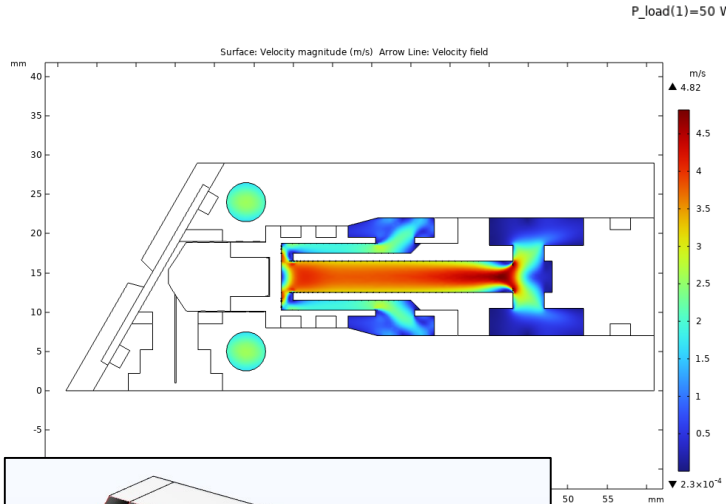
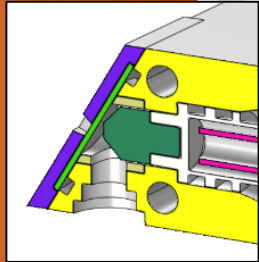


Our approach: nonisothermal flow and heat transfer (One-way coupling approach)



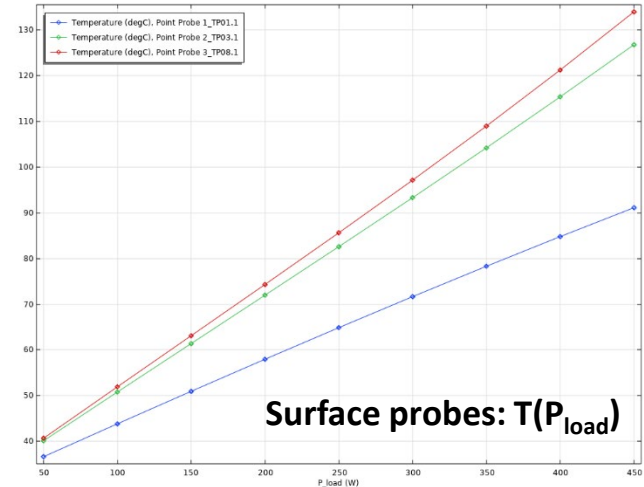
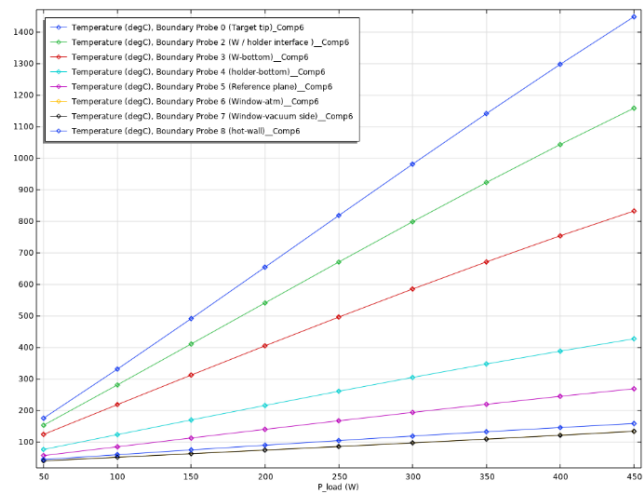
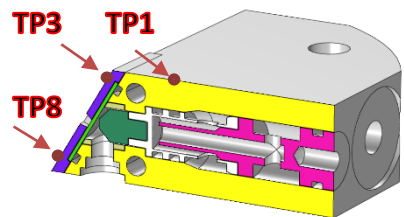
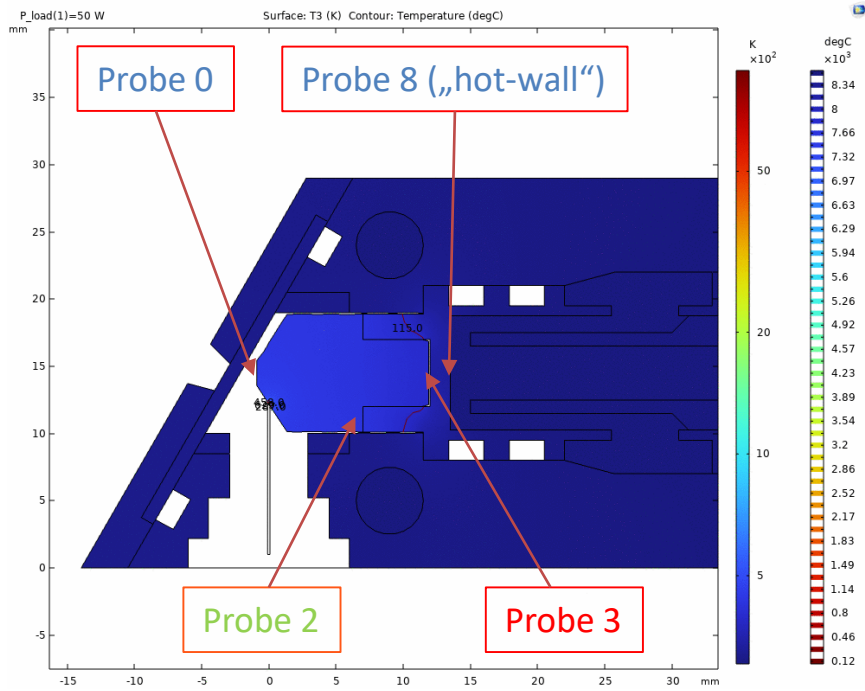
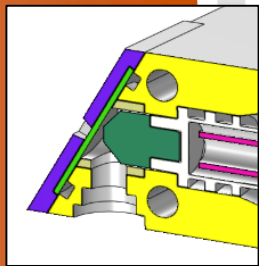
1) Nonisothermal Flow

2) Heat Transfer

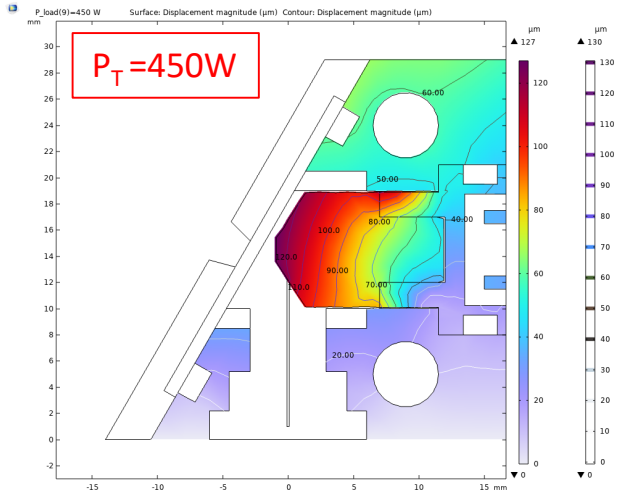
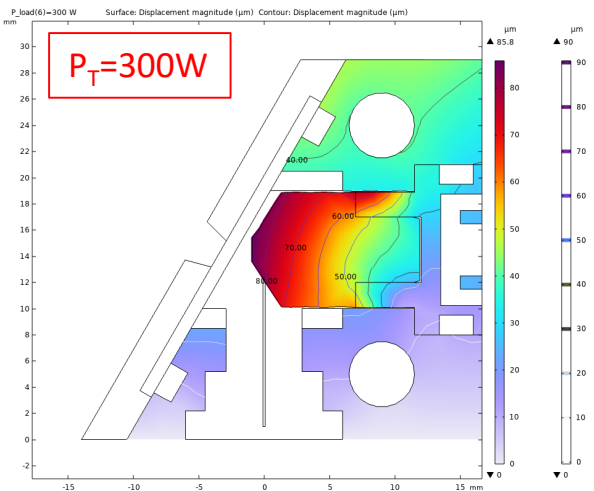
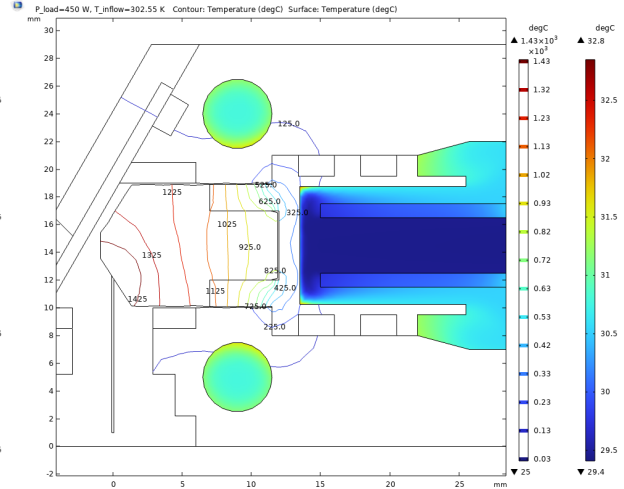
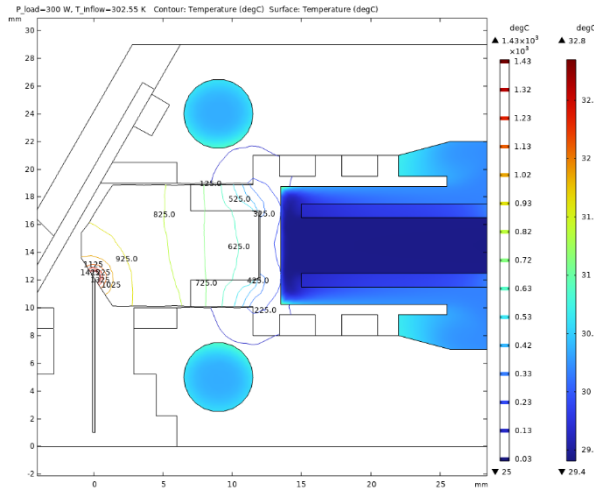
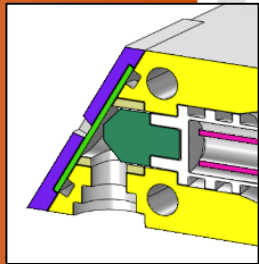


Surface probes are used to monitor temperatures; experimental data is available for reference

Modelling results (heat transfer)

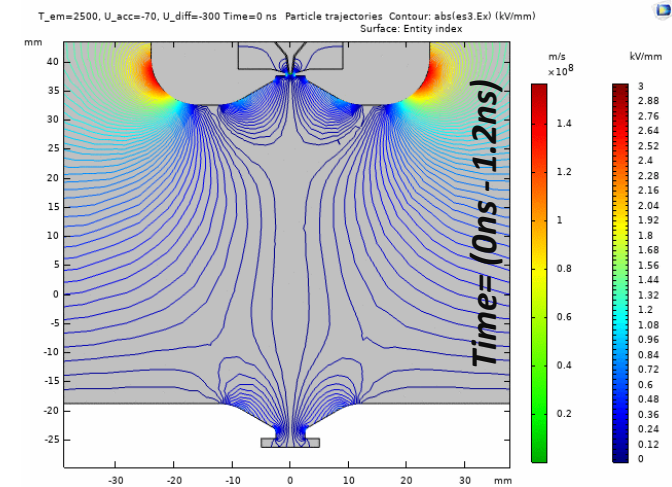
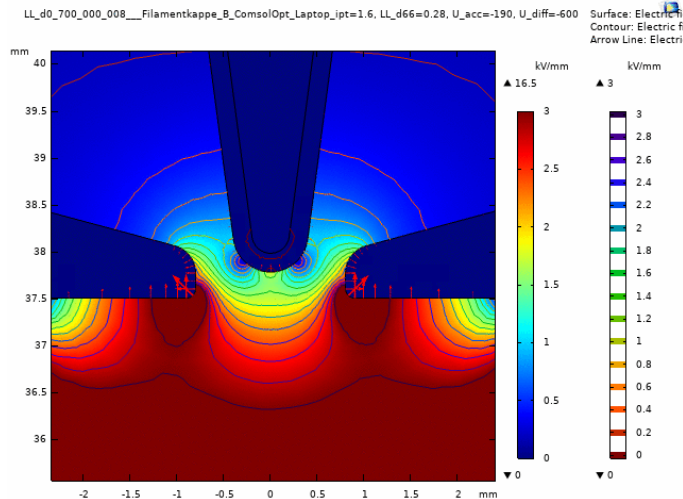
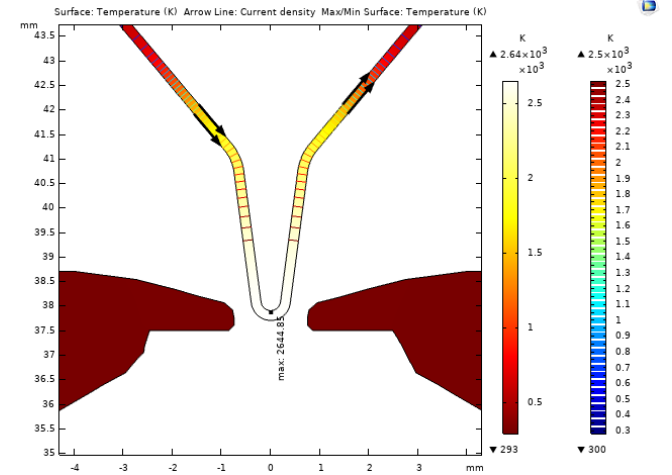
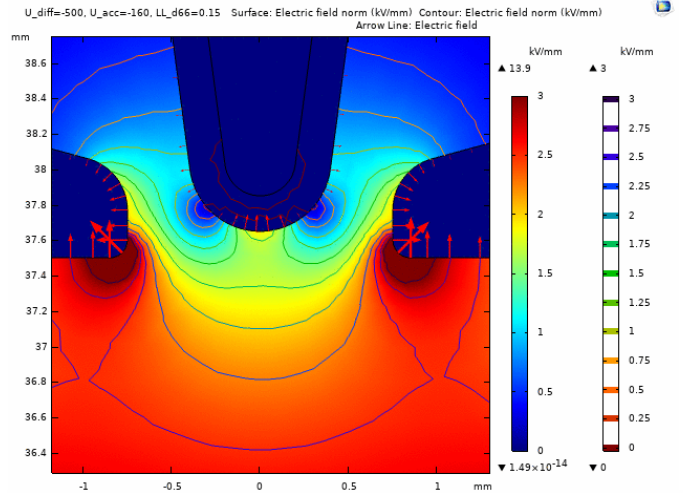
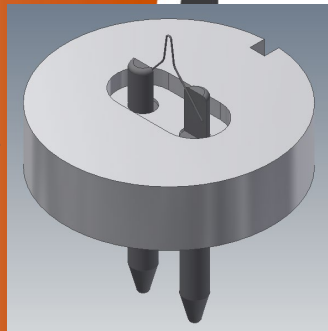
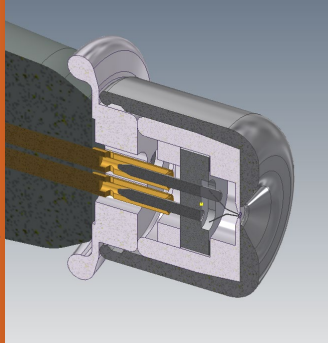


Modelling results (heat transfer and thermal expansion)

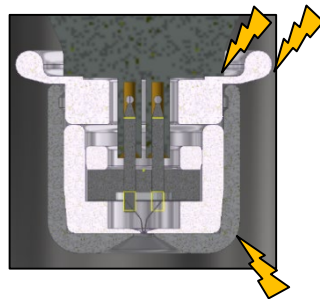
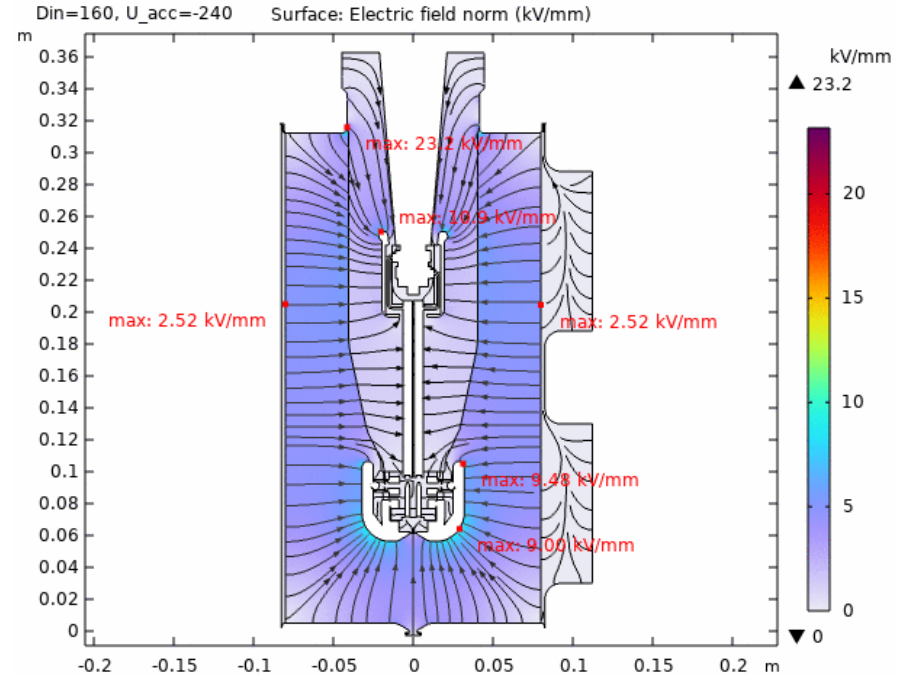
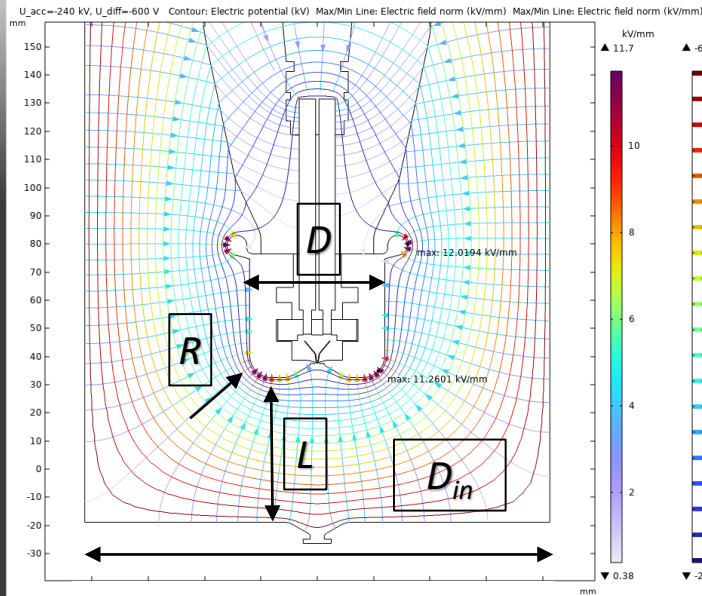


Target assembly:
design
optimization

Optimization of aperture diameter and filament position, particle tracing



Optimization of the geometry of the cathode chamber and cathode assembly



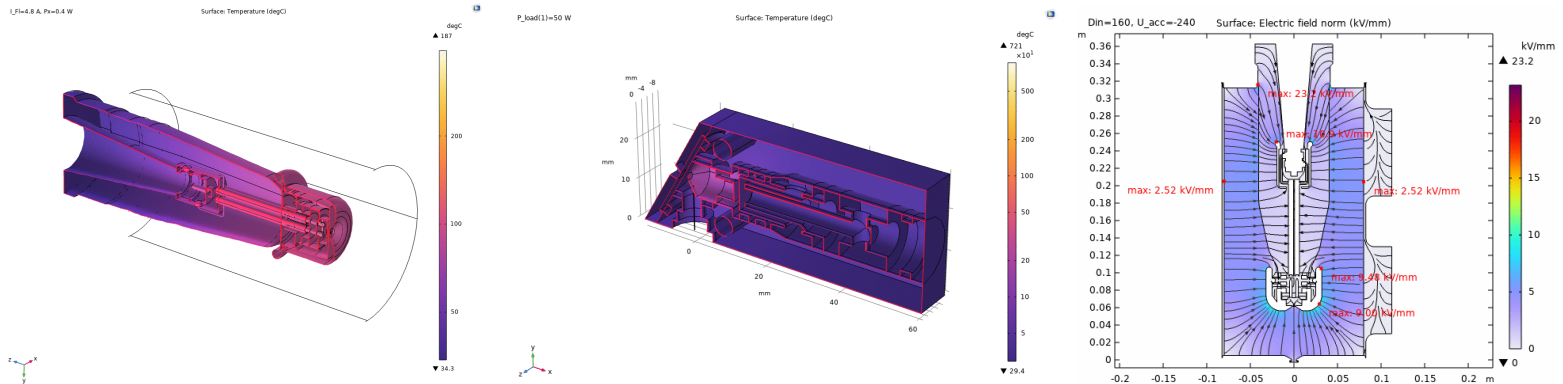
Minimization of local electrical field
(electrostatic, dielectric strength)

„Triple point“: very strong enhancement of the electric field
may take place due to the thermal expansion

Summary

Comsol application by X-Ray WorX incl.:

- Optimization of the thermal load on HV-Insulators and the target
- Optimization of aperture diameter and filament position, filament current and particle tracing
- Optimization of the geometry of the cathode chamber and cathode assembly





Thank you

Contact

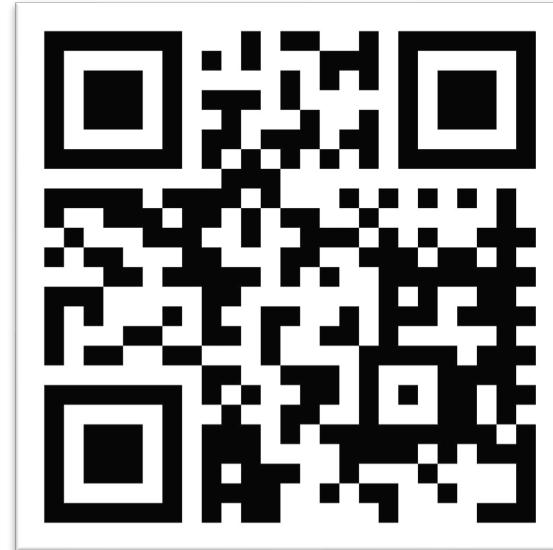


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Abstract



Modelling Of Thermal Load And Electric Fields In Microfocus X-ray Tubes

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Abstract

The thermal load on the system components is one of the technical problems in the development of microfocus X-ray tubes. To improve their stability in long-term use, it is important to understand the physical phenomena and their influence on the system stability and filament lifetime.

To improve our X-Ray WorX products, we apply Comsol Multiphysics software to optimize the thermal load on the insulators as well as the target used to generate the X-rays. Joule heating mechanism, used to facilitate thermionic emission from the filament, generate a lot of heat that must be dissipated by the cathode assembly and insulator. The insulators in particular can cause problems from a dielectric and mechanical point of view, since they experience relatively high temperatures and thermal expansion under thermal load in the presence of strong electric fields. The decisive factors here are the vacuum conditions, the temperature distribution, the dielectric insulation strength by high-voltage application of up to 300 kV and the mechanical construction. We apply FEM to address the issue of thermal management and dielectric strength and to optimize the mechanical design of our cathode assembly and insulator.